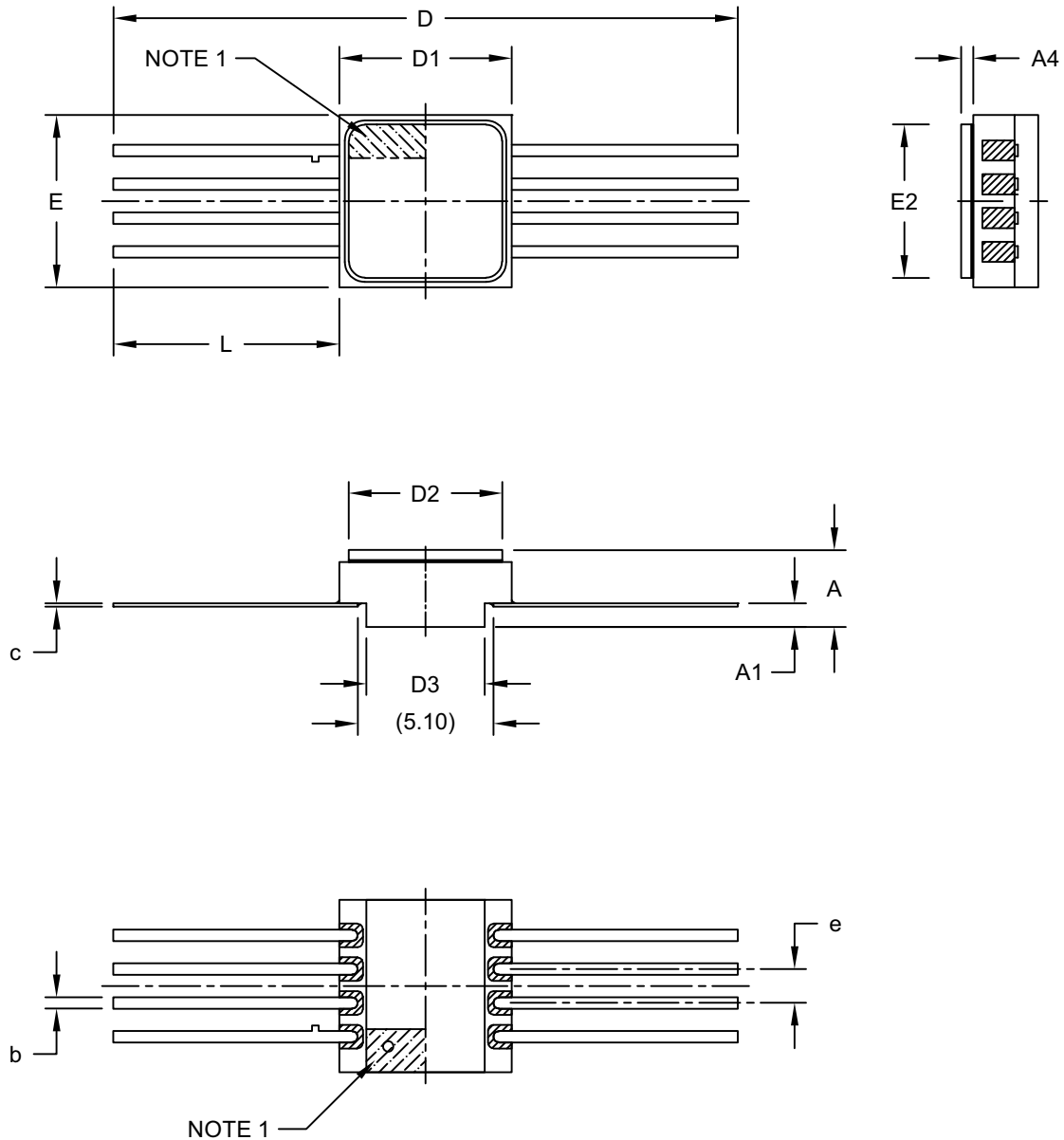


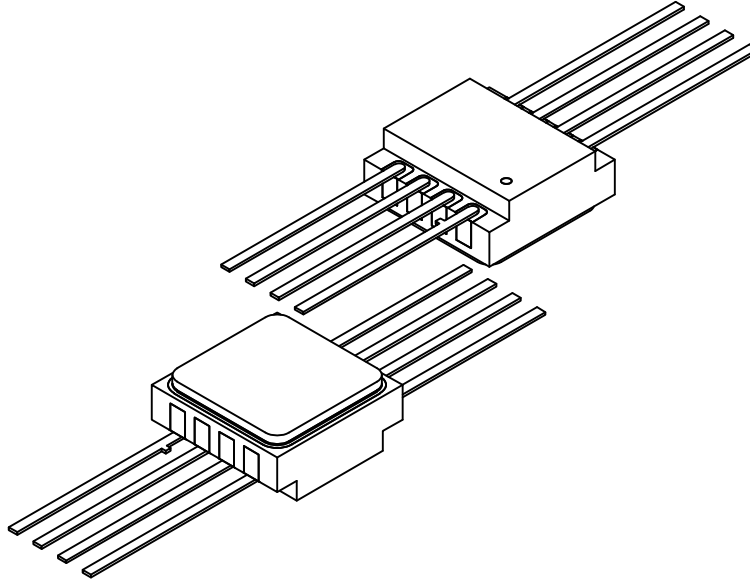
8-Lead Ceramic Multi Layer Flat Pack (3XB) - 6.485x6.485x2.89 mm Body [MFPF]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



8-Lead Ceramic Multi Layer Flat Pack (3XB) - 6.485x6.485x2.89 mm Body [MFPPF]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units	MILLIMETERS		
Dimension Limits	MIN	NOM	MAX
N	8		
e	1.22	1.27	1.32
A	2.64	2.89	3.14
A1	0.799	0.889	0.899
A4	0.379	0.38	0.381
D	—	—	23.50
D1	6.235	6.485	6.735
D2	5.777	5.780	8.783
D3	4.30	4.45	4.60
E	6.235	6.485	6.735
E2	7.92	8.00	6.735
b	0.382	0.432	0.482
c	0.77	0.127	0.177
L	8.128	8.508	8.888

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.